SCIENTECH

Scientech Corp (3583:TT)

M.T. Hsu 2025/02/24

Safe Harbor Statement

- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.

- Except as required by law, we undertake no obligation to update any forward-looking statements, whether as a result of new information, future events or otherwise.

Agenda

- Company Profile
- Products
- Corporate Governance
- Financial Results
- Future Prospect

ABOUT US

Overview | Milestones | Location | Certificate | Competence

Overview

SCIENTECH

Product and Technology

- Equipment Design and Manufacturing
- Wafer Reclaim
- Representative

Industries We Serve

- Semiconductor (Front-End and Advanced Packaging)
- Compound Semiconductor
- LED / Mini LED / Micro LED
- Flat Panel Display (TFT-LCD, AMOLED, Touch Panel)

Established:
1979
Taipei, Taiwan

Capital:
US$ 27 Million
TWSE:3583

Employees:
>1020
(Worldwide)

Staffs

Over 1020 Staffs

Representative

- 140 in Taiwan
- 130 in China
- 70% in Service and Process Support

Equipment Design and Maf'g

- 350 in Total
- 100+ in R&D, Process and Design

Wafer Reclaim

- 315 in Total

Administration

- 85 in Total

Milestones

SCIENTECH
1979

1985
Branch Office
in Hsinchu, Taiwan

1995
Subsidiary
in CA, USA

2001
Subsidiary
in Shanghai, China

2002
Singapore

2003
Equipment Manufacture
Department Established

2004
New Hsinchu
Office Opened

2006
Wafer Reclaim
Business Launched

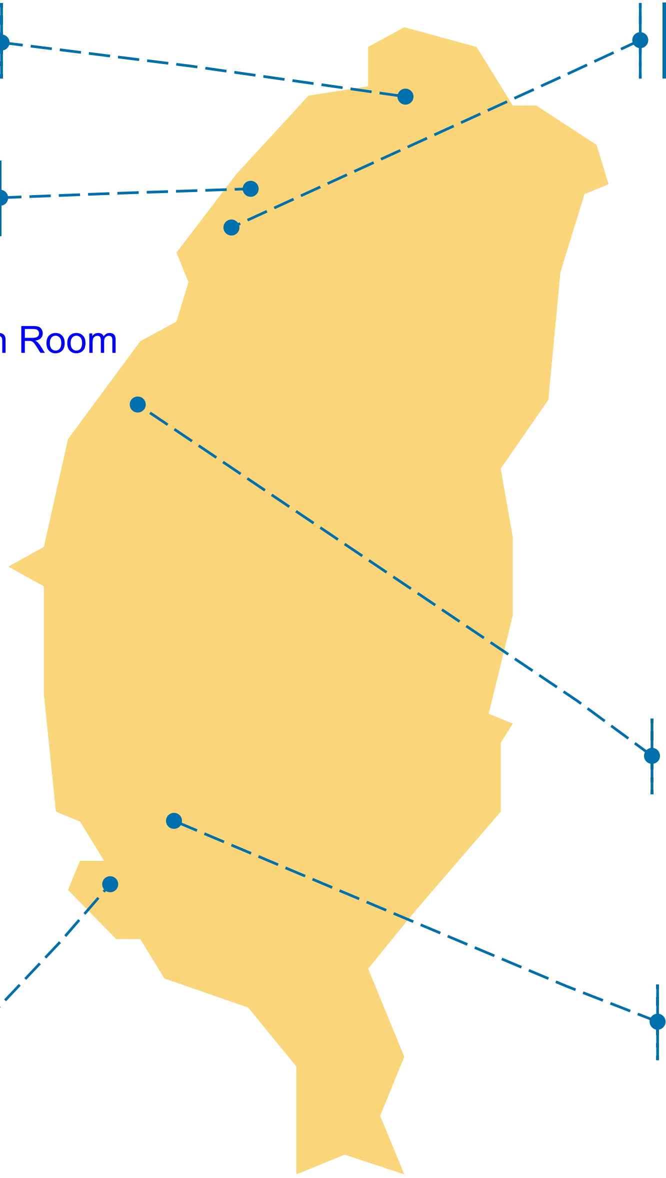
2007
New Factory
in Hukou Opened

2013
Publicly Listed in
Taiwan Stock Market

2019
Over 500 Equipment
Sales Achievement

2021
Subsidiary
in Villach, Austria

Locations - Taiwan



Taipei Headquarter

HuKou Factory

- Equipment Design and Manufacturing
  - Equipped With Class 10/1,000/10,000 Clean Room
- Wafer Reclaim

Kaohsiung Office

HsinChu Office

Taichung Office

Tainan Office

Locations - Worldwide

SCIENTECH

Europe

Villach, Austria (2020)

- Sales and Service Office to support European customers
- Interface with our factory and European Customers
- New Product / PRODUCTS Development

China

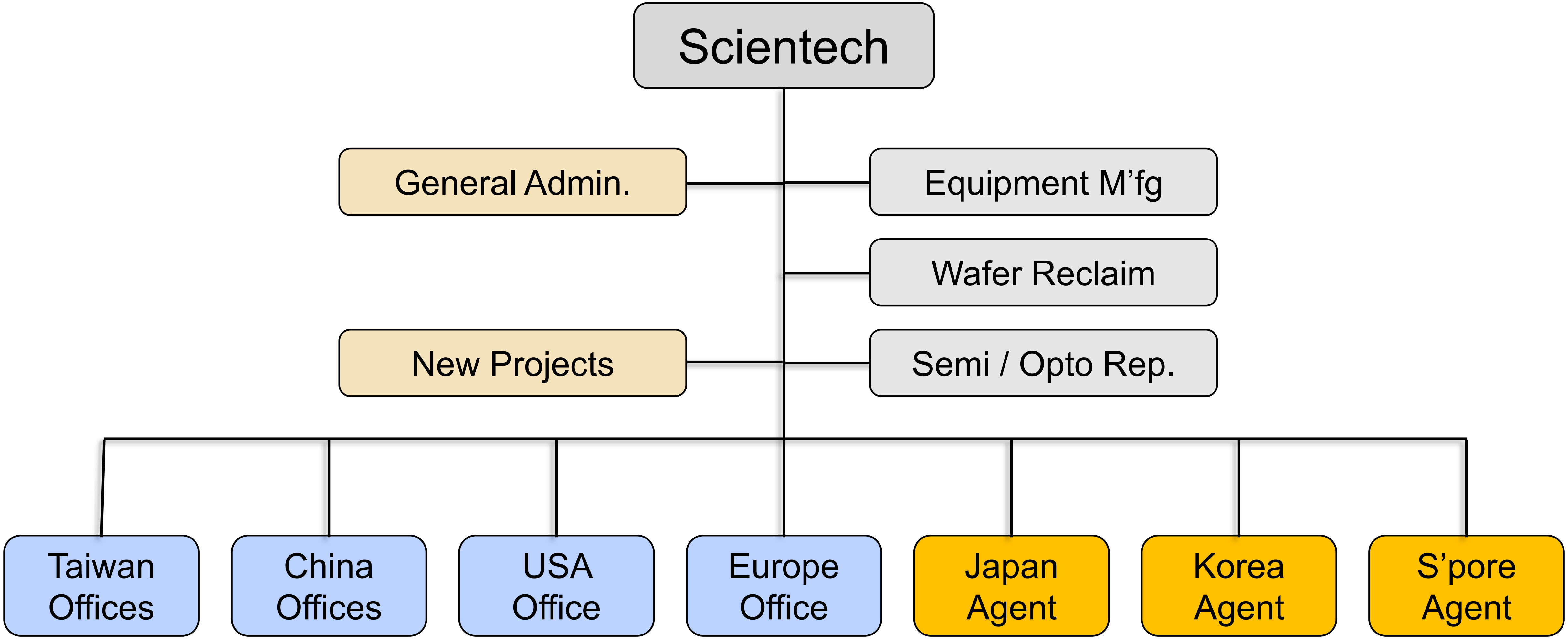
- Beijing office (2004)
- Dalian office (2012)
- Xian (2013)
- Chongqing office (2010)
- Changzhou (2012)
- Wuxi office (2003)
- Shanghai Office (2001)
- Wuhu office (2013)
- Xiamen office (2011)
- Huizhou office (2013)
- Qunming Office (2002)

USA

Santa Clara, CA (1994)

- Sales and Service Office
- Interface with Principals and U.S. Customers
- New Product / PRODUCTS Development

Organization



Scientech

General Admin.

New Projects

Equipment M'fg

Wafer Reclaim

Semi / Opto Rep.

Taiwan Offices

China Offices

USA Office

Europe Office

Japan Agent

Korea Agent

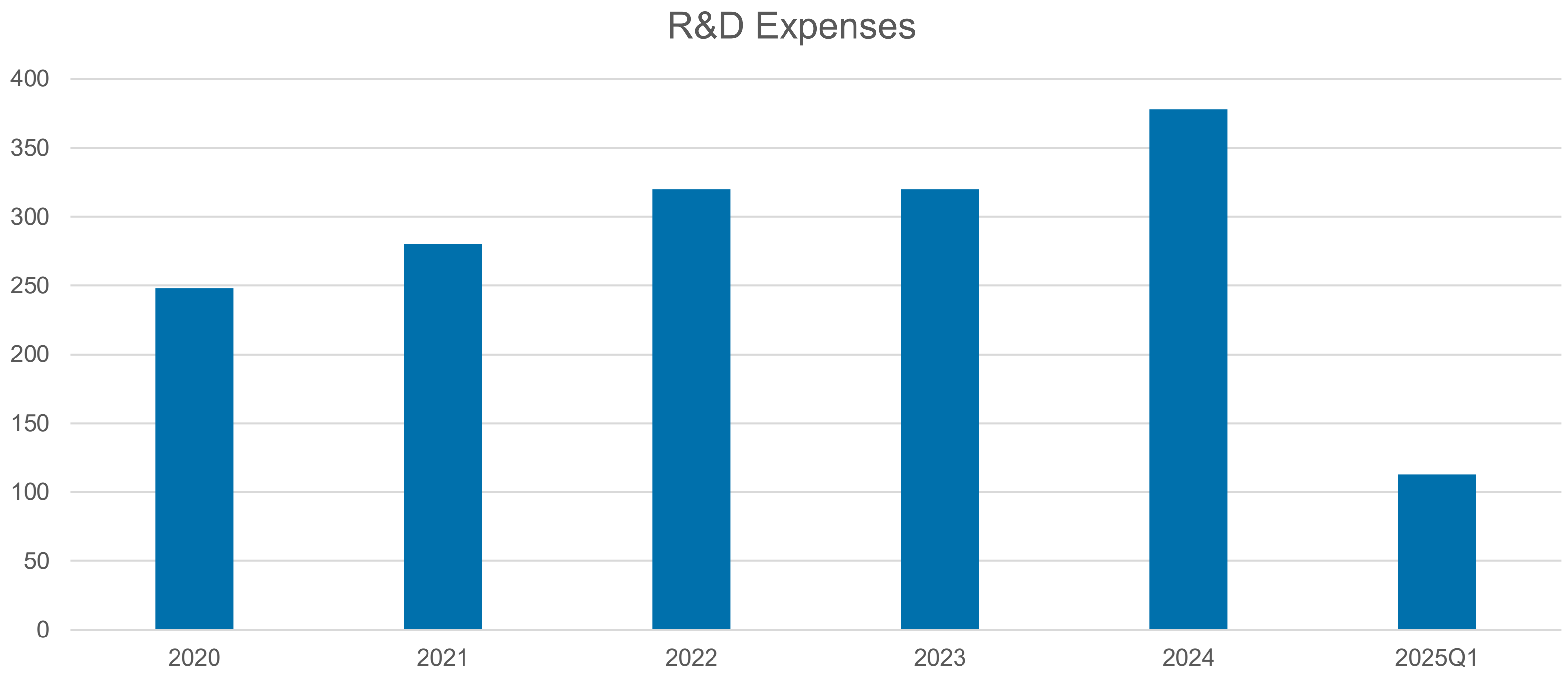
S'pore Agent

PRODUCTS

Wafer Reclaim | Equipment Manufacturing and Design | Representative

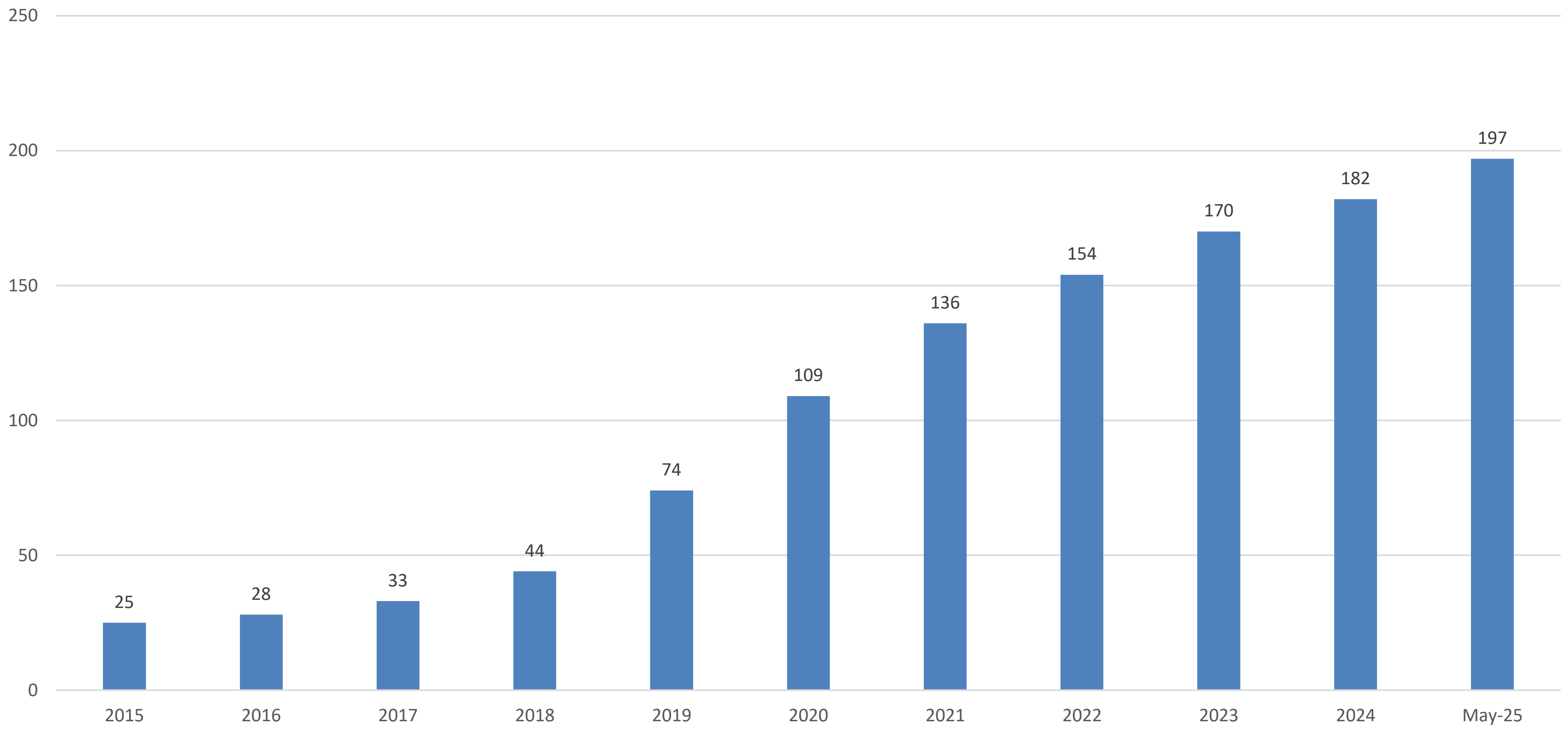
R&D Expenses

Units NT $ M	2020	2021	2022	2023	2024	2025Q1
R&D Expenses	248	280	320	341	378	113
Expenses as % of Revenue	6.9%	6.0%	5.7%	4.9%	3.9%	4.0%
Expenses as % of Manufacturing	16.5%	14.9%	15.3%	15.7%	11.3%	10.8%



R&D Patents Number

- **The cumulative number of patents on file is 197, and 52 applications are pending.**



Products

Equipment Design and Manufacturing

- Advanced Package
- FEOL
- Mask
- Compound
- etc...

Wafer Reclaim

- 12” Si Wafer

Representative

- Equipment/Metrology
- Sub-System
- Material
- Repair and Refurbish

Wafer Reclaim Service

Advanced Clean Technology
- **19nm Particle**
- **Low Trace Metal (<1E9)**

Advanced Defect Inspection (SP1/SP2/SP5/SP7)

12” Si Wafer

- Capacity: 160K / Month
- Cu and Non-Cu Process

Capacity Expansion

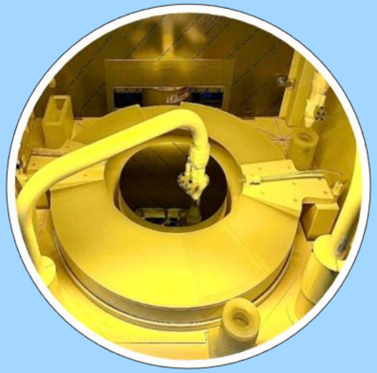
- Additional 50K / Month by end of 2025

Complete Polishing Process
- **Single/Double Side Polish**
- **Final Haze Polish**

Super Flatness (GBIR < 0.5mm)

Equipment Design & Manufacturing

Wet Bench



Single Wafer

TBDB

Baking

Wet Process – Bench

Application

- Semiconductor: FEOL, BEOL, Compound
- Advanced Packaging/Bumping…

Features

- Cassette type or Cassette-less type
- Adopted by big international companies
- Leading-edge technologies

Process

- Etch: Metal/Oxide/Nitride remove
- Stripper: PR/PI strip, Polymer remove
- Clean: Pre/Post/Flux clean
- Electro-less Plating: Zn/Ni/Pd/Au

Equipment Design & Manufacturing

SCIENTECH

Wet Process – Single Wafer

Application

- Semiconductor: BEOL, FEOL, Compound
- Advanced Packaging/Bumping

Features

- Soak/Immersion + Single
- Adopted by big international companies
- Leading-edge technologies

Process

- UBM / Metal Etch
- Flux Clean (Hot DIW)
- PR Strip
- Wafer Clean (APC, Soft spray)
- Final Clean/Mask Clean/Frame Clean

Temporary Bonding De-Bonding

Application

- IGBT & SiC Power Device
- Advanced Packaging for Semiconductor

Features

- User-friendly graphical user interface
- Adopted by big international companies
- Leading-edge technologies

Process

- Temporary Bonding
- Temporary De-bonding
- Release Layer Coating
- Carrier (Glass) Recycling

Moisture Baking

Application

- Semiconductor: BEOL
- Advanced Packaging for Semiconductor

Features

- Availability for horizontal or vertical process
- High precision temperature control
- Weight handling capacity up to 23kg per lot

Process

- Pre-underfill baking
- Pre-mold baking
- DFR Hard Bake

Trading (Agent/Distributor)

TMC

BRUKER

Vistec Electron Beam

MueTec Measurement and Inspection

HPSP High Pressure Solution Provider

Canon

Trymax PLASMA TECHNOLOGY SOLUTIONS

NOVA PROCESS INSIGHT

KLA

MDC VACUUM PRODUCTS, LLC

SMEE

ZEISS

Multiple Apps

Exclusivity

Long Term Partnership

ADVANCED ENERGY

USHIO

Plasma-Therm

VLSI Standards Incorporated

RUDOLPH RESEARCH ANALYTICAL

TMC

YES

FRT

KINGSEMI

FILMETRICS

ExOne DIGITAL PART MATERIALIZATION

Kensington LABORATORIES

Verity INSTRUMENTS, INC.

Representative Product Lines

Lithography

KINGSEMI

SMEE

vistec
Electron Beam

ESOL

USHIO

Etch

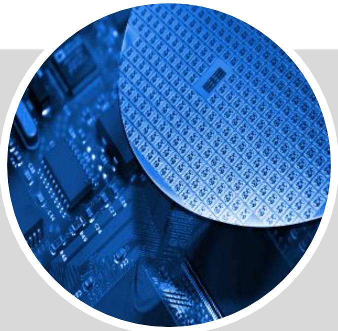
Plasma-Therm

CORIAL

Trymax
PLASMA TECHNOLOGY SOLUTIONS

MEMS tek
GLOW THE FUTURE

Verity
INSTRUMENTS, INC.



Thin Film

ClassOne
TECHNOLOGY

Intlvac
THIN FILM

ProOptics

AXUS
TECHNOLOGY

Diffusion

HPSP
High Pressure Solution Provider

Representative Product Lines

Metrology

KLA
FILMETRICS
ZEISS
Camtek
VLSI Standards Incorporated
MueTec Measurement and Inspection
SURUGA SEIKI
YAYATECH
Rigaku
Toho Technology

Sub-Systems

Advanced Energy
MDC PRECISION
TMC / AMETEK
Verity INSTRUMENTS, INC.
CORE INSIGHT 코어인사이트(주)
UNEO
AMETEK Haydon kerk Motion Solutions
PITTMAN

Package & Material

PacTech
sempro
SANYOSEIKO CO.,LTD.
MIRTEC
MODU TECH
GP 群翊 GROUP
M Napra
AMC Quality & Service
Cygnus
Univertical Global Benchmark of Quality

Robot Repair and Refurbish

Genmark
Kensington LABORATORIES
MILARA
Dynatronix

Corporate Governance

Certificates

2007

ISO 9001

Quality Management

2010

ISO 14001

Environmental Management

2016

TIPS

Taiwan Intellectual Property Management

2018

ISO 45001

Occupational Health and Safety Management

2019

ISO 27001

Information Security Management

2021

ISO 22301

Business Continuity Management

2022

RBA

Responsible Business Alliance Online Member

2024

ISO 50001

Energy Management

ESG

Sustainability Report Officially Released in 2024/08

Sustainable Development

Environmental

Social

Governance

Eco-Friendly Manufacturing

Safe And Warm Working Environment

Operating With Integrity

Contributing To Society

Exhibition

SEMICON

Semicon China

Mar. 26-28, 2025
Shanghai

SEMICON

Semicon TW

Sep. 10-12, 2025
Taipei

SEMICON

Semicon West

Oct. 07–09, 2025
Phoenix

SEMICON

Semicon Europa

Nov. 18-21, 2025
Munich

Exhibition

ISES

May 13-14, 2025
Taipei

ECTC

May 27-30, 2025
Dallas, Texas

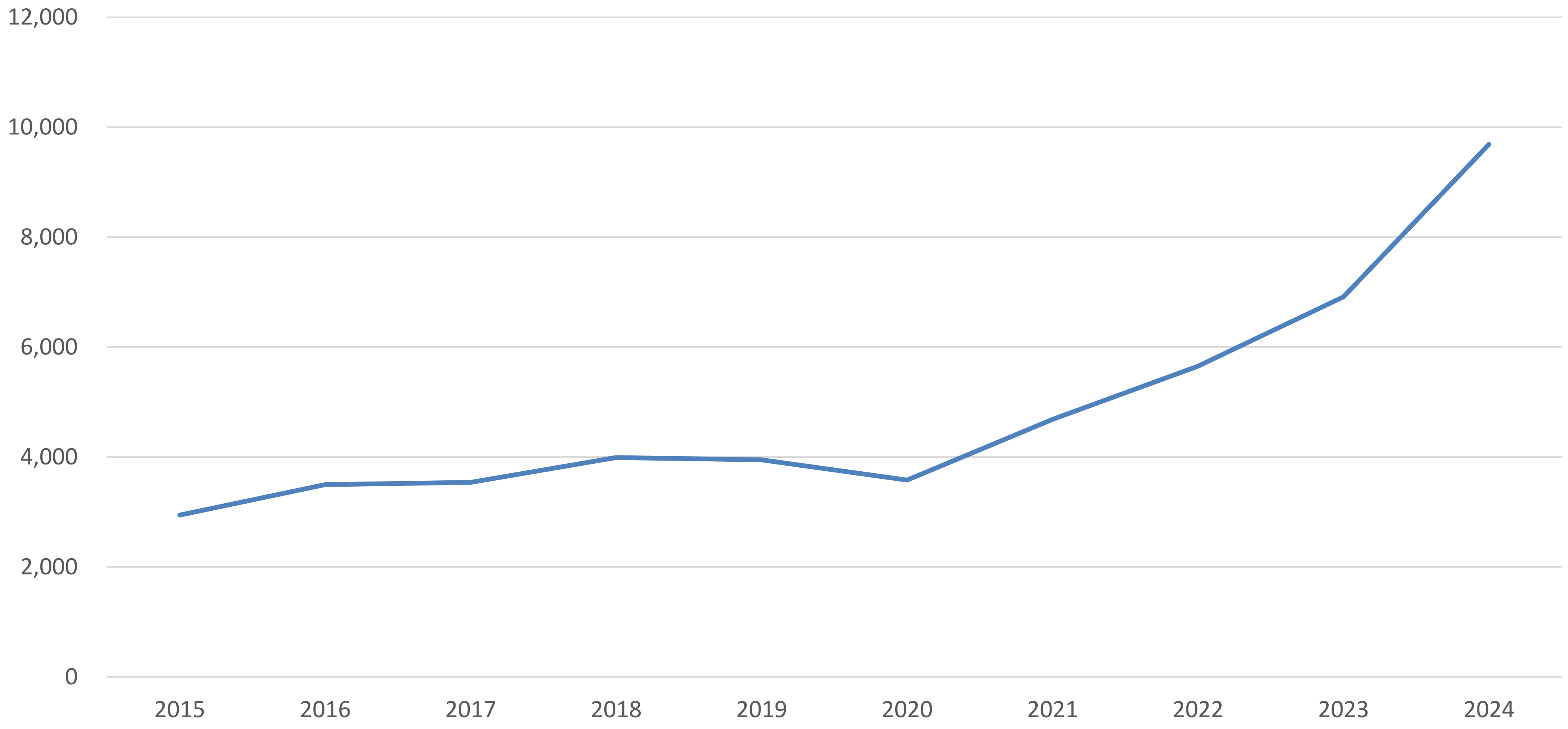
Financial Results

Income Statement

Units：NT $ M	2020	2021	2022	2023	2024	2025Q1
Revenues	3,580	4,684	5,650	6,911	9,688	2,812
Gross Profit	1,456	1,667	2,084	2,201	2,906	893
Operating Expenses	991	1,112	1,374	1,483	1,790	545
Operating Income	465	555	710	718	1116	349
Income Before Tax	389	524	736	860	1277	367
Net Income	305	420	568	650	927	257
EPS	**3.80**	**5.23**	**7.08**	**8.10**	**11.54**	**3.20**
Gross Margin	41%	36%	37%	32%	30%	32%
Operating Margin	13%	12%	13%	10%	12%	12%
Income Before Tax Margin	11%	11%	13%	12%	13%	13%

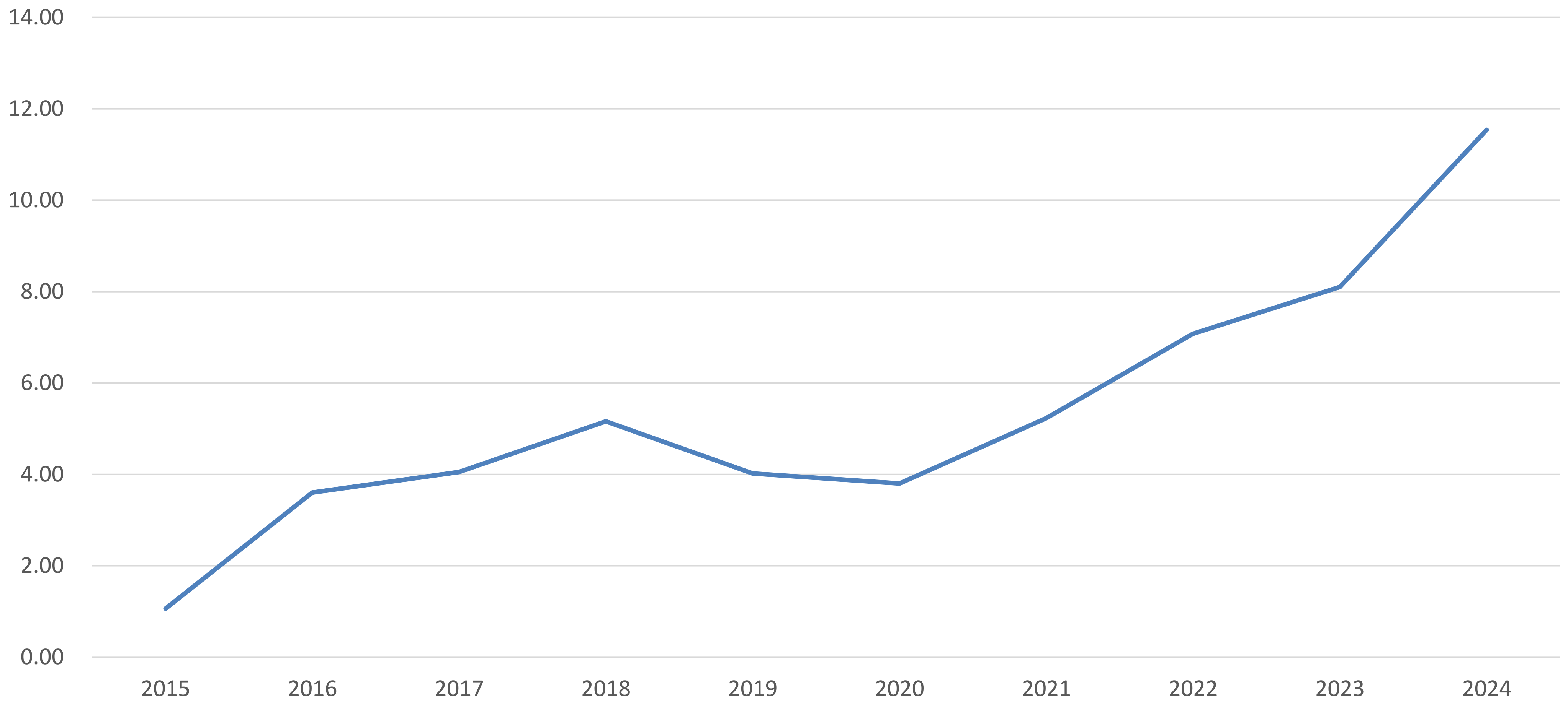
Revenue

Units NT $ M	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025Q1
Revenue	2,942	3,495	3,539	3,988	3,949	3,580	4,684	5,650	6,911	9,688	2,813



EPS

	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025Q1
EPS	1.06	3.6	4.05	5.16	4.02	3.8	5.23	7.08	8.1	**11.54**	**3.20**



Future Prospect

Industry Outlook

- The CAGR of the Semi. market size over the next 10 years is approximately 8%
- In 2025, the global Semi. market is expected to grow 11%
- Driven by demand in artificial intelligence (AI) and high-performance computing applications, the semi. market in Taiwan:

Year	Market Size (Billion US$)	Groth Rate (%)
2024	165	22
2025	187	16.5

- 12-inch semi. advanced process continues to thrive
  - **Front-End**: 5nm、3nm、2nm、1nm
  - **Advanced Package:** Fan-Out、2.5D (CoWoS)、3D (SoIC)…etc

Industry Outlook – 2

SCIENTECH

- **The CAGR of Advanced Packaging over the next 10 years is estimated at 11%.**
- **CoWoS production capacity is expanding substantially to meet the rising demand for AI chip applications**
- **AI applications are expanding from data centers to personal devices**
- **China's semi. production capacity is expanding, intensifying price competition in mature process nodes.**
- **Compound Semi:**
  - **Investment in electric vehicles (EVs) and 5G is stagnant**
  - **Mobile phone demand is saturating, leading to reduced GaAs production**
  - **SiC demand gradually increases, with new capacities slowing down**
  - **Micro LED adoption is progressing slowly**

Expansion Plan

SCIENTECH

- 2023: New equipment production base in Hukou (off-site)
- 2024: Expansion of existing equipment production at Hukou Plant
- **2025 Q4: Wafer Reclaim Capacity 50K/Month at Hukou Plant**
- **2026 Q4: 9,000 M-Square new building (Plant II) for equipment manufacturing, and warehouse next to Hukou Plant (Plant I)**
- **2026 Q4: Wafer Reclaim Capacity 30K/Month at Hukou Plant**
- **2027 Q1: 20,000 M-Square new building for equipment manufacturing, and warehouse in Tainan (southern Taiwan)**
- 2027: Wafer Reclaim Capacity 50K/Month at Hukou Plant

SCIENTECH

Thank You!

https://www.scientech.com.tw